

Replace the current Abstract of the Disclosure with the following:

A method for forming an embedded low profile capacitor in a multilayer printed circuit board. The method entails providing a first metal plate on a dielectric substrate. A dielectric layer of a photopolymeric material is applied onto a first region of the first metal plate, surrounded by a second region that is exposed. A second metal plate is deposited onto the dielectric layer and the second region of the first metal plate. The second plate is then patterned to decline an upper electrode on the dielectric layer that is electrically isolated from the first metal plate. This may be accomplished by forming a trench in the second metal plate above the dielectric layer. In one aspect, the resulting capacitor thus comprises a lower electrode structure derived mainly from the first metal plate, a dielectric layer overlying the first region of the first metal plate and an upper electrode overlying the dielectric layer. The lower metal structure also includes an extension deposited onto the second region of the first metal layer about the dielectric layer and including a lip overlying a perimeter of the dielectric layer surface.